SDAS163B - DECEMBER 1982 - REVISED NOVEMBER 2004

- 3-State Buffer-Type Outputs Drive Bus Lines Directly
- Bus-Structured Pinout

description/ordering information

These 8-bit D-type transparent latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

While the latch-enable (LE) input is high, the Q outputs follow the complements of data (D) inputs. When LE is taken low, the outputs are latched at the inverse of the levels set up at the D inputs.

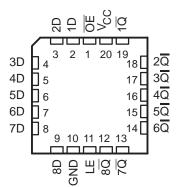
A buffered output-enable (\overline{OE}) input places the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased high logic level provide the capability to drive bus lines without interface or pullup components.

OE does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

SN54ALS563B J OR W PACKAGE
SN74ALS563B DW, N, OR NS PACKAGE
(TOP VIEW)

	(,	
OE	1	U ₂₀] v <u>c</u> c
1D	2	19] 1 <u>Q</u>
2D	3	18	2Q
3D	4	17] 3Q
4D	5	16] 4Q
5D	6	15] 5Q
6D	7	14] 6Q
7D	8	13] 7Q
8D	9	12] 8Q
GND	10	11	LE

SN54ALS563B ... FK PACKAGE (TOP VIEW)



ORDERIN	G INFO	ORMATIC	N

TA	PACKAGE	t	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74ALS563BN	SN74ALS563BN
0°C to 70°C		Tube of 25	SN74ALS563BDW	AL 0500D
	SOIC – DW	Reel of 2000	SN74ALS563BDWR	ALS563B
	SOP – NS	Reel of 2000	SN74ALS563BNSR	ALS563B
	CDIP – J	Tube of 20	SNJ54ALS563BJ	SNJ54ALS563BJ
–55°C to 125°C	CFP – W	Tube of 85	SNJ54ALS563BW	SNJ54ALS563BW
	LCCC – FK	Tube of 55	SNJ54ALS563BFK	SNJ54ALS563BFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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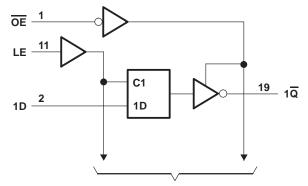
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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FUNCTION TABLE (each latch)									
	INPUTS		OUTPUT						
OE	LE	Q							
L	Н	Н	L						
L	Н	L	н						
L	L	Х	Q ₀						
Н	Х	Х	Z						

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

	5.5 V
	DW package
	N package 69°C/W
	NS package 60°C/W
Storage temperature range, T _{stg}	−65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network ground terminal.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

		SN	SN54ALS563B			SN74ALS563B			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.7			0.8	V	
ЮН	High-level output current			-1			-2.6	mA	
IOL	Low-level output current			12			24	mA	
tw	Pulse duration, LE high	15			15			ns	
t _{su}	Setup time, data before LE \downarrow	20			10			ns	
th	Hold time, data after LE \downarrow	12			10			ns	
TA	Operating free-air temperature	-55		125	0		70	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	7507.00	TEST CONDITIONS				SN74ALS563B			
PARAMETER	TEST CO	INDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	lı = – 18 mA			-1.2			-1.2	V
	V_{CC} = 4.5 V to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	VCC -	2		VCC -	2		
VOH		$I_{OH} = -1 \text{ mA}$	2.4	3.3					V
	$V_{CC} = 4.5 V$	$I_{OH} = -2.6 \text{ mA}$				2.4	3.2		
		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 24 mA					0.35	0.5	V
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ
I _{OZL}	V _{CC} = 5.5 V,	V _O = 0.4 V			-20			-20	μΑ
l	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
IН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
١ _{١L}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
۱ ₀ ‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
		Outputs high		10	17		10	17	
Icc	V _{CC} = 5.5 V	Outputs low		16	26		16	26	mA
		Outputs disabled		17	29		17	29	

[†] All typical values are at V_{CC} = 5 V, T_A = 25° C.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



SN54ALS563B, SN74ALS563B OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS SDAS163B – DECEMBER 1982 – REVISED NOVEMBER 2004

switching characteristics (see Figure 1)

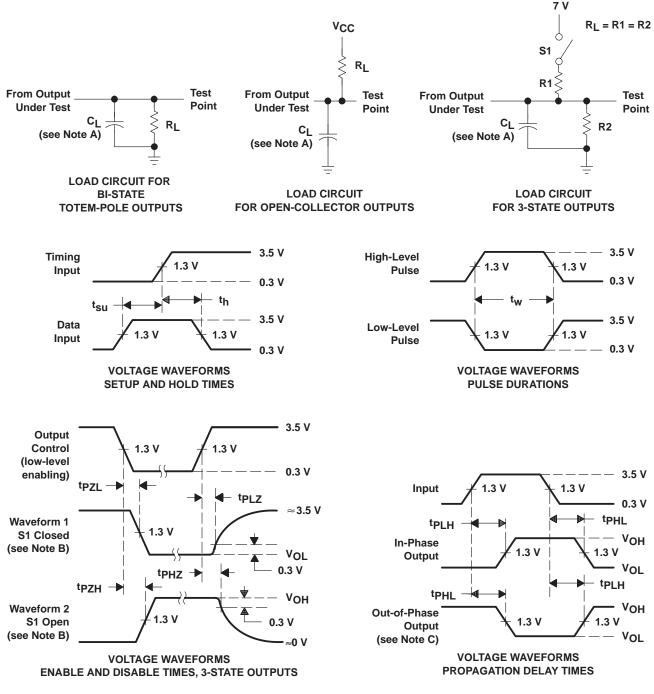
PARAMETER	FROM (INPUT)	то (оитрит)	С _І R1 R2 Тд	_ = 50 pl l = 500 2 = 500 4 = MIN 1	2 2 0 MAX†		UNIT
			SN54AL	S563B	SN74AL	S563B	
			MIN	MAX	MIN	MAX	
^t PLH	P	ā	3	26	3	18	
^t PHL	D	D Q		15	3	14	ns
^t PLH		ā	8	29	6	22	
^t PHL	LE	Q	4	22	6	21	ns
^t PZH	OE	ā	4	25	3	18	
^t PZL	ÛE	Q	4	21	4	18	ns
^t PHZ	ŌĒ	Q	2	12	1	10	
^t PLZ	UE	Q	3	22	1	15	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_f = t_f = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
	()				-	()	(6)	(-)			
5962-8870001RA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8870001RA SNJ54ALS563BJ	Samples
SN74ALS563BDW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS563B	Samples
SN74ALS563BN	ACTIVE	PDIP	Ν	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS563BN	Samples
SN74ALS563BNSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS563B	Samples
SN74ALS563BNSRG4	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS563B	Samples
SNJ54ALS563BJ	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8870001RA SNJ54ALS563BJ	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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PACKAGE OPTION ADDENDUM

13-Aug-2021

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS563B, SN74ALS563B :

- Catalog : SN74ALS563B
- Military : SN54ALS563B

NOTE: Qualified Version Definitions:

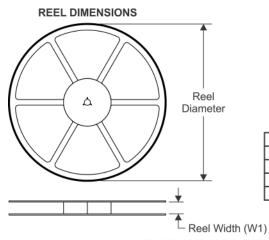
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

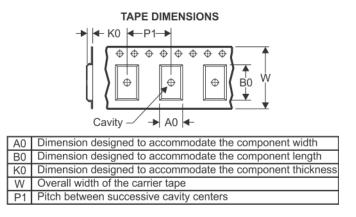
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS563BNSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1



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PACKAGE MATERIALS INFORMATION

5-Jan-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS563BNSR	SO	NS	20	2000	367.0	367.0	45.0



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5-Jan-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN74ALS563BDW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ALS563BN	N	PDIP	20	20	506	13.97	11230	4.32

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



DW0020A

EXAMPLE BOARD LAYOUT

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DW0020A

EXAMPLE STENCIL DESIGN

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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